

L Number	Hits	Search Text	DB	Time stamp
11	1		USPAT	2004/06/23 18:59
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32	1		USPAT	2004/06/23 19:02
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36	1		USPAT	2004/06/23 19:03
37	1		USPAT	2004/06/23 19:03
38	1		USPAT	2004/06/23 19:03
39	1		USPAT	2004/06/23 19:03
40	1		USPAT	2004/06/23 19:04
41	1		USPAT	2004/06/23 19:04
42	0		USPAT	2004/06/23 19:04
43	54	"5994166"	USPAT	2004/06/23 19:04
46	383	257/777 and (solder or ball or bump) and (capacitor or resistor)	USPAT	2004/06/23 21:16
47	26	(257/777 or 257/686) and (solder or ball or bump) and (silicon or "Si") near (die or chip or semiconductor or IC) with memory	USPAT	2004/06/23 21:19
48	207	(257/777 or 257/686) and (solder or ball or bump) and (silicon or "Si") near (die or chip or semiconductor or IC) and memory	USPAT	2004/06/23 21:19
-	5	6081029.pn. or 5942794.pn. or 5623162.pn. or 5578871.pn. or 5371044.pn.	USPAT	2004/06/22 14:21
-	1	"6639306"	USPAT	2004/06/22 14:25
-	0	"20010033011"	USPAT	2004/06/22 14:25
-	1	"20010033011"	USPAT; US-PGPUB	2004/06/22 14:25
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:25
-	1		USPAT	2004/06/22 14:25
-	464	(semiconductor or die or chip or IC) and (die near pad or paddle) with (protrusion\$4 or tab)	USPAT	2004/06/22 15:07
-	10	(semiconductor or die or chip or IC) and (die near pad or paddle) with (indentation\$4)	USPAT	2004/06/22 14:46
-	5894	(semiconductor or die or chip or IC) and (lead) with (protrusion\$4 or tab or indentation\$3)	USPAT	2004/06/22 14:47
-	909	((semiconductor or die or chip or IC) and (lead) with (protrusion\$4 or tab or indentation\$3)) and 438/\$.ccles.	USPAT	2004/06/22 14:48
-	1		USPAT	2004/06/22 14:49
-	1		USPAT	2004/06/22 14:50
-	1		USPAT	2004/06/22 14:50
-	1		USPAT	2004/06/22 14:51
-	1		USPAT	2004/06/22 14:51
-	1		USPAT	2004/06/22 14:51



-	1618	438/123	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/06/22 18:46
-	1187	438/124	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/06/22 19:08
-	1628	438/127	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/06/22 19:27
-	3151	257/666	USPAT	2004/06/22 19:28
-	3167	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/06/22 19:54
-	4566	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/06/23 11:29
-	3904	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/06/23 11:32
-	3388	257/778	USPAT	2004/06/23 11:32
-	2754	257/778 and solder	USPAT	2004/06/23 11:32
-	610	257/778 and solder with (big\$3 or larg\$2)	USPAT	2004/06/23 11:55
-	1327	257/777 and solder	USPAT	2004/06/23 11:56
-	1585	257/777 and (solder or ball or bump)	USPAT	2004/06/23 19:16
-	45	257/777 and (solder or ball or bump)	JPO	2004/06/23 12:56
-	1622	257/686 and (solder or ball or bump)	USPAT; JPO	2004/06/23 12:58
-	9	"6297960"	USPAT	2004/06/23 15:56

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-	1	"6639306"	USPAT	2004/06/22 14:25
-	0	"20010033011"	USPAT	2004/06/22 14:23
-	1	"20010033011"	USPAT; US-PGPUB	2004/06/22 14:23
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:24
-	1		USPAT	2004/06/22 14:25
-	1		USPAT	2004/06/22 14:25
-	1		USPAT	2004/06/22 14:25
-	464	(semiconductor or die or chip or IC) and (die near pad or paddle) with (protrus\$4 or tab)	USPAT	2004/06/22 15:07
-	10	(semiconductor or die or chip or IC) and (die near pad or paddle) with (indentat\$4)	USPAT	2004/06/22 14:46
-	5894	(semiconductor or die or chip or IC) and (lead) with (protrus\$4 or tab or indentat\$3)	USPAT	2004/06/22 14:47
-	909	((semiconductor or die or chip or IC) and (lead) with (protrus\$4 or tab or indentat\$3)) and 438/\$.ccls.	USPAT	2004/06/22 14:48
-	1		USPAT	2004/06/22 14:49
-	1		USPAT	2004/06/22 14:50
-	1		USPAT	2004/06/22 14:50
-	1		USPAT	2004/06/22 14:51
-	1		USPAT	2004/06/22 14:51
-	1		USPAT	2004/06/22 14:51



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-	3167	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/06/22 19:54
-	4566	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/06/23 11:29
-	3904	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/06/23 11:32
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-	9	"6297960"	USPAT	2004/06/23 15:56